#### Nch 650V 7A Power MOSFET

$V_{DSS}$	650V
R <sub>DS(on)</sub> (Max.)	0.665Ω
I <sub>D</sub>	±7A
$P_D$	78W

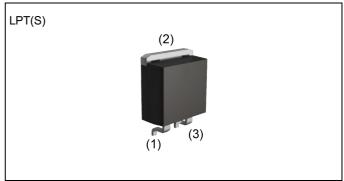
#### Features

- 1) Low on-resistance
- 2) Ultra fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

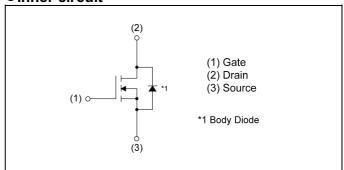
### Application

Switching

#### Outline



#### •Inner circuit



Packaging specifications

Packing	Embossed Tape
Packing code	TL
Marking	R6507KNJ
Basic ordering unit (pcs)	1000

### ullet Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V <sub>DSS</sub>	650	V
Continuous drain current (T <sub>c</sub> = 25°C)		I <sub>D</sub> *1	±7	Α
Pulsed drain current	I <sub>DP</sub> *2	±21	Α	
Gate - Source voltage static  AC(f>1Hz)		V	±20	V
		V <sub>GSS</sub>	±30	V
Avalanche current, single pulse		I <sub>AS</sub>	1.3	А
Avalanche energy, single pulse		E <sub>AS</sub> *3	136	mJ
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	78	W	
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage temper	ature range	T <sub>stg</sub>	-55 to +150	°C

#### ●Thermal resistance

Downwortow	Cymah al	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *4	-	-	1.6	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *5	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

## ●Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumbal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	650	-	-	V
		V <sub>DS</sub> = 650V, V <sub>GS</sub> = 0V				
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	100	μΑ
aram carron		$T_j = 125^{\circ}C$	-	-	1000	
Gate - Source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
Gate threshold voltage V <sub>GS(</sub>		$V_{DS} = V_{GS}, I_{D} = 200 \mu A$	3	-	5	V
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 2.4A				
Static drain - source on - state resistance	R <sub>DS(on)</sub> *6	$T_j = 25^{\circ}C$	-	0.605	0.665	Ω
		$T_j = 125^{\circ}C$	-	-	-	
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	3.2	-	Ω

### ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatar	Cymah al	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	470	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	470	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	20	-	
Turn - on delay time	t <sub>d(on)</sub> *6	$V_{DD} \simeq 300V$ , $V_{GS} = 10V$	-	20	-	
Rise time	t <sub>r</sub> *6	I <sub>D</sub> = 3.5A	-	20	-	
Turn - off delay time	t <sub>d(off)</sub> *6	$R_L \simeq 86.6\Omega$	-	35	-	ns
Fall time	<b>t</b> <sub>f</sub> *6	$R_G = 10\Omega$	-	25	-	

### ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumb al	Conditions	Values			Unit	
Parameter	Symbol	ool Conditions –		Тур.	Max.	Offic	
Total gate charge	$Q_g^{*6}$	V <sub>DD</sub> ≈ 300V	-	14.5	-		
Gate - Source charge	Q <sub>gs</sub> *6	I <sub>D</sub> = 7A	-	4.2	-	nC	
Gate - Drain charge	${\sf Q_{gd}}^{*6}$	V <sub>GS</sub> = 10V	-	5.8	-		
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 300V, I <sub>D</sub> = 7A	-	6.9	-	V	

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L $\doteqdot$ 100mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>i</sub>=25 $^{\circ}$ C

<sup>\*4</sup> T<sub>C</sub>=25°C

<sup>\*5</sup> Mounted on an epoxy PCB FR4 (25mm x 27mm x 0.8mm)

<sup>\*6</sup> Pulsed

### ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Cymbol	Conditions		Unit			
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Source current	I <sub>S</sub> *1	T - 25°C	-	-	7	Α	
Pulsed source current	I <sub>SP</sub> *2	T <sub>C</sub> = 25°C	-	-	21	Α	
Source-Drain voltage	V <sub>SD</sub> *6	$V_{GS} = 0V, I_{S} = 7A$	-	-	1.5	٧	
Reverse recovery time	t <sub>rr</sub> *6		-	320	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *6	I <sub>S</sub> = 7A di/dt = 100A/μs	-	2.7	-	μC	
Peak reverse recovery current	<sub>rr</sub> *6		-	17	-	А	

Fig.1 Power Dissipation Derating Curve

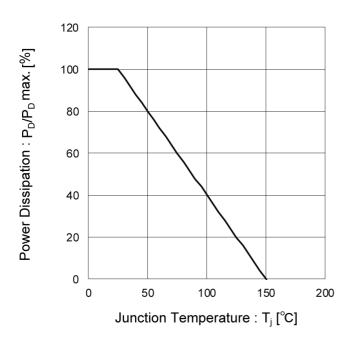


Fig.2 Drain Current Derating Curve

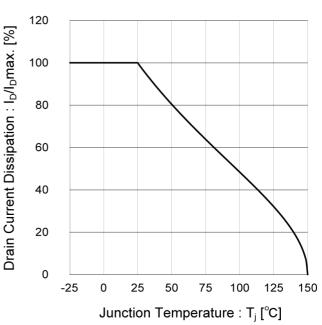


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

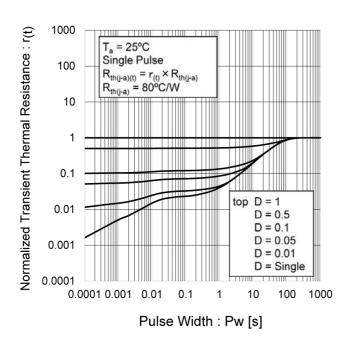
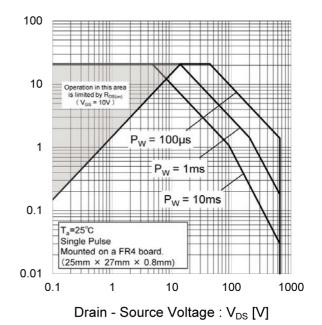


Fig.4 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Fig.5 Avalanche Energy Derating Curve

120 Avalanche Energy: EAS / EAS max [%] 100 80 60 40 20 0 0 25 50 75 100 125 175 Junction Temperature : T<sub>j</sub> [°C]

Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

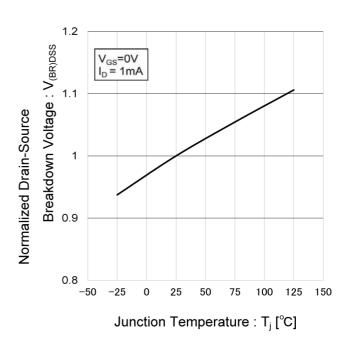


Fig.7 Typical Output Characteristics(I)

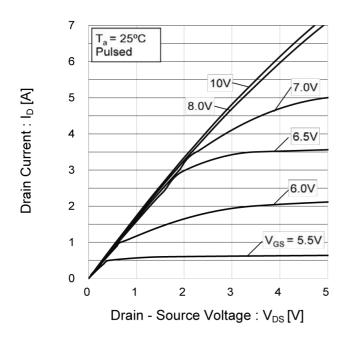
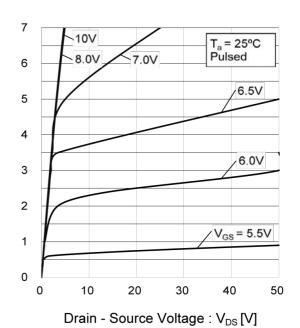


Fig.8 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Fig.9 Typical Transfer Characteristics

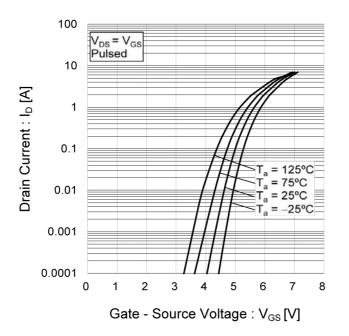


Fig.10 Normalized Gate Threshold

Voltage vs. Junction Temperature

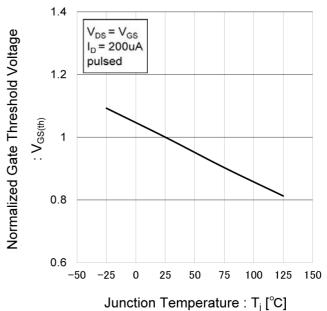


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

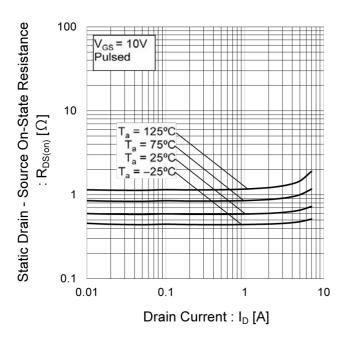


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

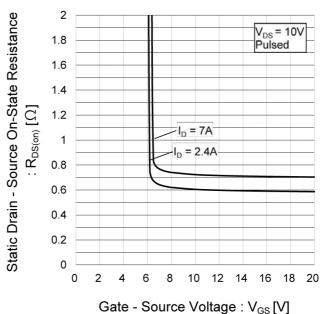


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

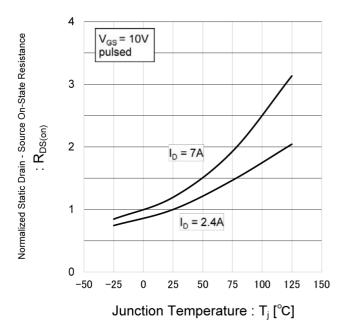


Fig.14 Typical Capacitance vs.

Drain - Source Voltage

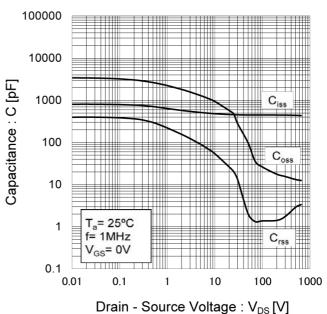


Fig.15 Switching Characteristics

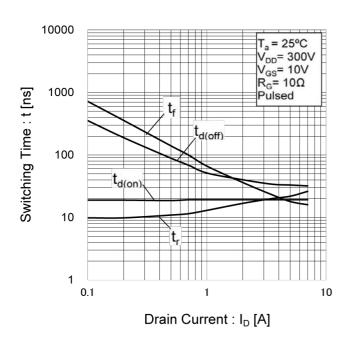
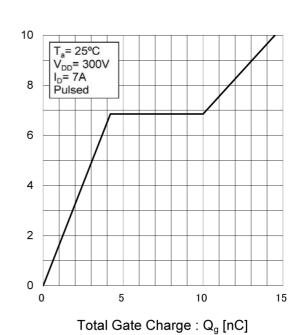
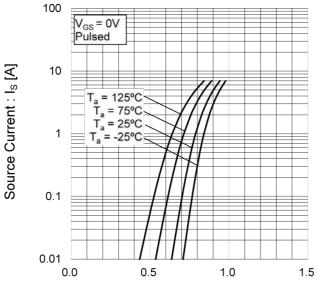


Fig.16 Typical Gate Charge



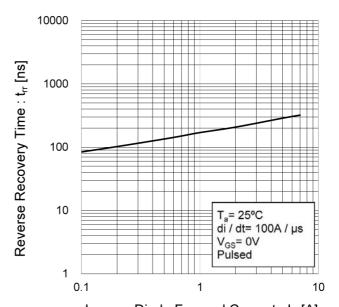
Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.17 Source Current vs. Source - Drain Voltage



Source - Drain Voltage : V<sub>SD</sub> [V]

Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current :  $I_S$  [A]

#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

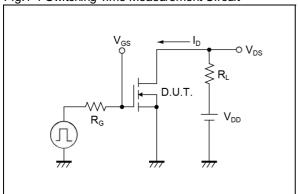


Fig.2-1 Gate Charge Measurement Circuit

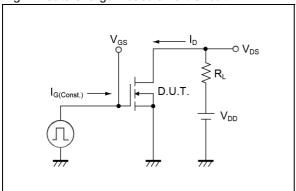


Fig.3-1 Avalanche Measurement Circuit

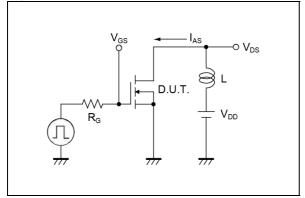


Fig.4-1 trr Measurement Circuit

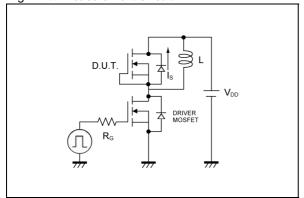


Fig.1-2 Switching Waveforms

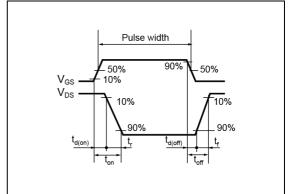


Fig.2-2 Gate Charge Waveform

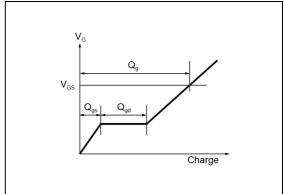


Fig.3-2 Avalanche Waveform

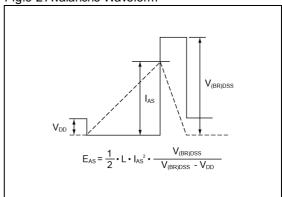
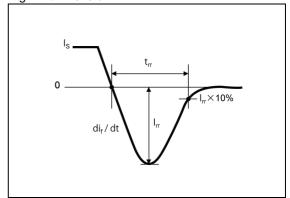
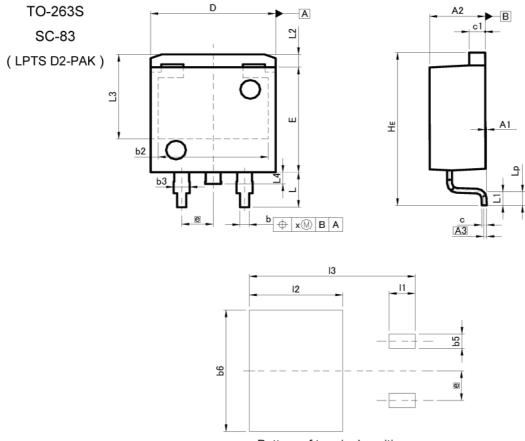


Fig.4-2 trr Waveform



### Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.9	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
cl	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	1.	20	0.0	47
L2	1.	10	0.0	143
L3	7.:	25	0.2	85
L4		00		39
Lp	0.90	1.50	0.035	0.059
Х	=======================================	0.25	-	0.010
DIM	MILIM	ETEDO	INC	LIEC

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
bb	E.c	1.23	-	0.049
b6	<b>4</b> 0	10.40	3=4	0.409
11	23	2.10		0.083
12	<del>70</del> 8	7.55	1.75	0.297
13		13.40	-	0.528

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSIII	CLASS II b	CLASSⅢ
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
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  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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